

**General Description**

- Trench Power MOSFET technology
- Low  $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS and Halogen-Free Compliant

**Applications**

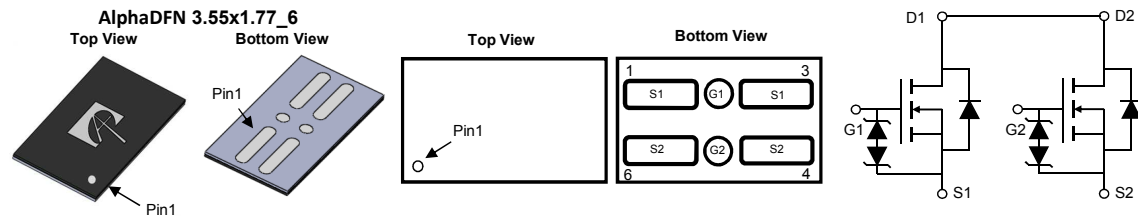
- Battery protection switch
- Mobile device battery charging and discharging

**Product Summary**

$V_{SS}$	12V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$ )	< 3m $\Omega$
$R_{SS(ON)}$ (at $V_{GS}=4.0V$ )	< 3.1m $\Omega$
$R_{SS(ON)}$ (at $V_{GS}=3.8V$ )	< 3.2m $\Omega$
$R_{SS(ON)}$ (at $V_{GS}=3.1V$ )	< 3.5m $\Omega$
$R_{SS(ON)}$ (at $V_{GS}=2.5V$ )	< 4.4m $\Omega$

**Typical ESD protection**

**HBM Class 2**



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOC3862	AlphaDFN 3.55x1.77_6	Tape & Reel	5000

**Absolute Maximum Ratings  $T_A=25^\circ C$  unless otherwise noted**

Parameter	Symbol	Rating	Units
Source-Source Voltage	$V_{SS}$	12	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Source Current(DC) <sup>Note1</sup>	$I_S$	27	A
Source Current(Pulse) <sup>Note2</sup>	$I_{SM}$	100	
Power Dissipation <sup>Note1</sup>	$P_D$	2.5	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient $t \leq 10s$	$R_{\theta JA}$	40	$^\circ C/W$
Maximum Junction-to-Ambient Steady-State		50	$^\circ C/W$

**Note 1.**  $I_S$  rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

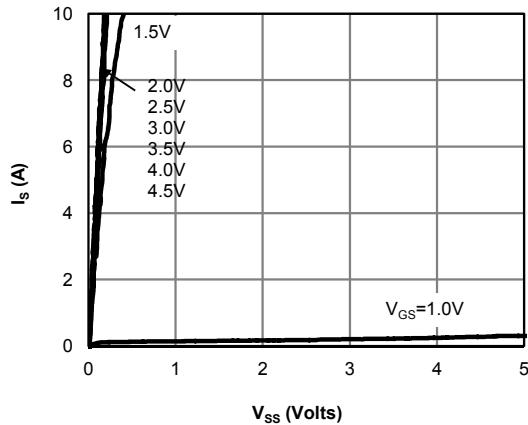
**Note 2.** PW < 10  $\mu s$  pulses, duty cycle 1% max.

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

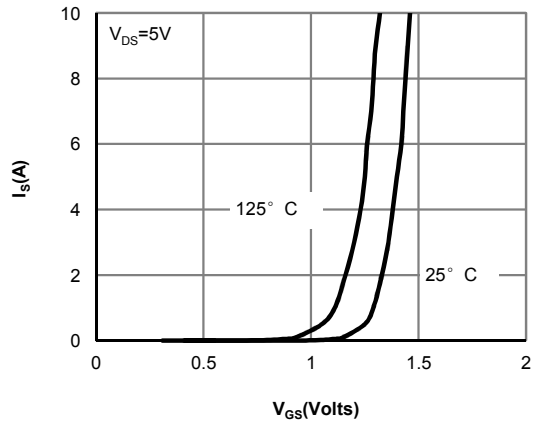
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>SSS</sub>	Source-Source Breakdown Voltage	I <sub>S</sub> =250μA, V <sub>GS</sub> =0V Test Circuit 6	12			V
I <sub>SSS</sub>	Zero Gate Voltage Source Current	V <sub>SS</sub> =12V, V <sub>GS</sub> =0V Test Circuit 1 T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate leakage current	V <sub>SS</sub> =0V, V <sub>GS</sub> =±8V Test Circuit 2			±10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>SS</sub> =V <sub>GS</sub> , I <sub>S</sub> =250μA Test Circuit 3	0.4	0.8	1.2	V
R <sub>SS(ON)</sub>	Static Source to Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>S</sub> =5A Test Circuit 4 T <sub>J</sub> =125°C	1.7	2.38	3.0	mΩ
			2.3	3.3	4.1	
		V <sub>GS</sub> =4.0V, I <sub>S</sub> =5A Test Circuit 4	1.75	2.45	3.1	mΩ
		V <sub>GS</sub> =3.8V, I <sub>S</sub> =5A Test Circuit 4	1.8	2.5	3.2	mΩ
		V <sub>GS</sub> =3.1V, I <sub>S</sub> =5A Test Circuit 4	1.9	2.7	3.5	mΩ
		V <sub>GS</sub> =2.5V, I <sub>S</sub> =5A Test Circuit 4	2.2	3.2	4.4	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>SS</sub> =5V, I <sub>S</sub> =5A Test Circuit 3		50		S
V <sub>FSS</sub>	Forward Source to Source Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V Test Circuit 5		0.65	1	V
<b>DYNAMIC PARAMETERS</b>						
R <sub>g</sub>	Gate resistance	f=1MHz		1.2		KΩ
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>G1S1</sub> =4.5V, V <sub>SS</sub> =6V, I <sub>S</sub> =5A		46		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>G1S1</sub> =4.5V, V <sub>SS</sub> =6V, R <sub>L</sub> =1.2Ω, R <sub>GEN</sub> =3Ω Test Circuit8		2.5		μs
t <sub>r</sub>	Turn-On Rise Time			5.5		μs
t <sub>D(off)</sub>	Turn-Off DelayTime			4		μs
t <sub>f</sub>	Turn-Off Fall Time			11		μs

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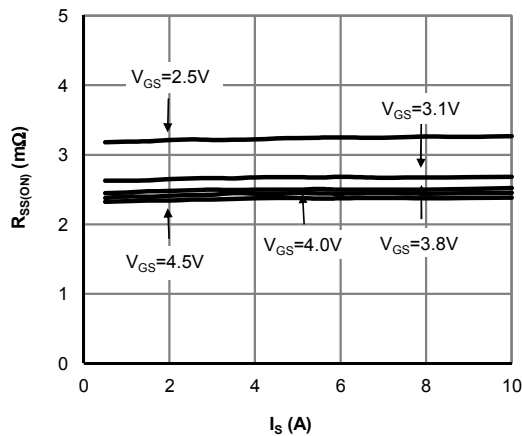
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



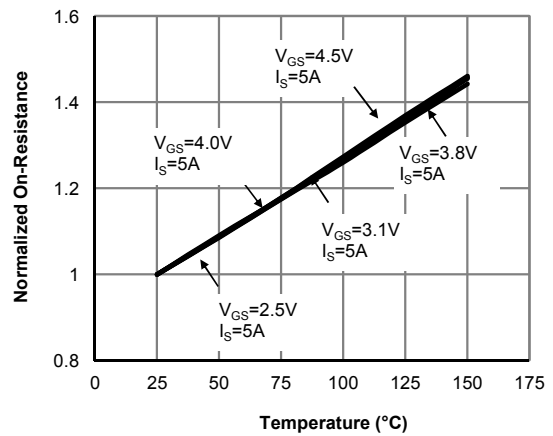
**Figure 1: On-Region Characteristics**



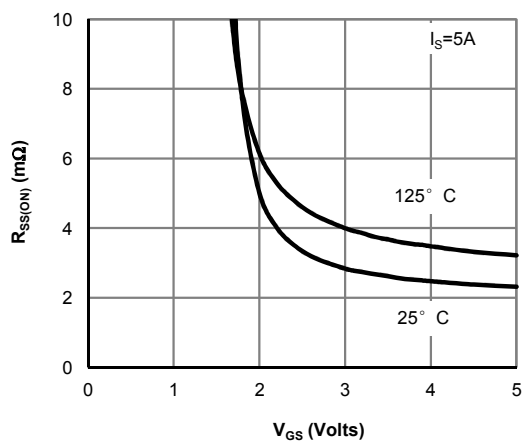
**Figure 2: Transfer Characteristics**



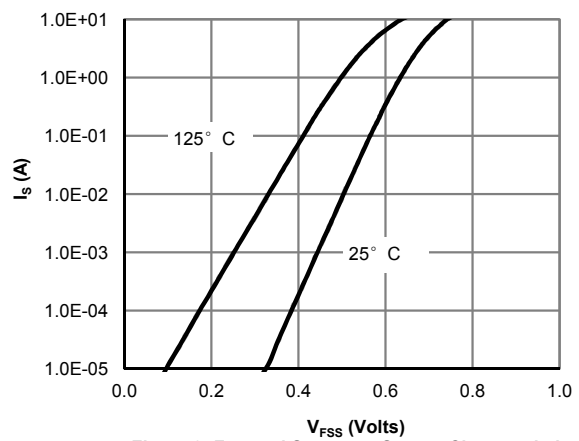
**Figure 3: On-Resistance vs. Source Current and Gate Voltage**



**Figure 4: On-Resistance vs. Junction Temperature**

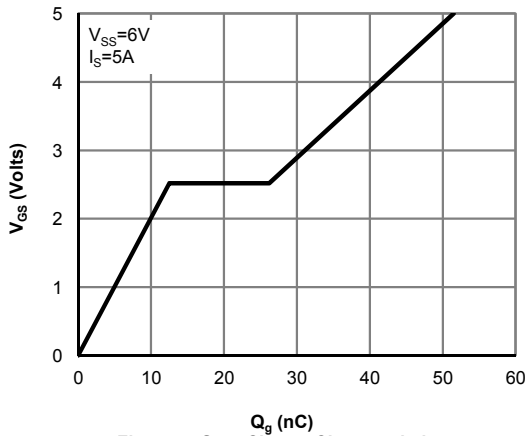


**Figure 5: On-Resistance vs. Gate-Source Voltage**

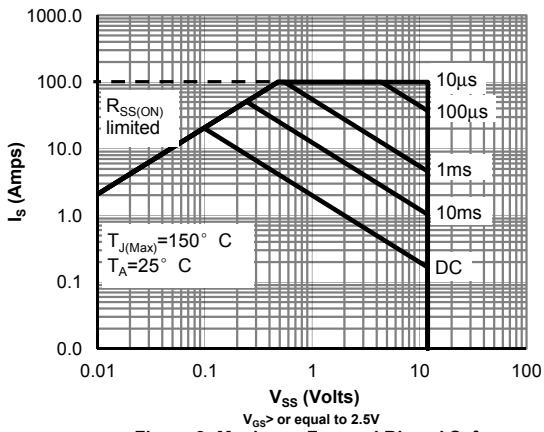


**Figure 6: Forward Source to Source Characteristics**

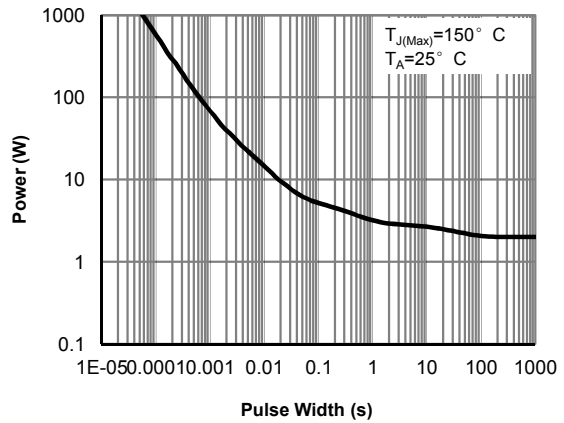
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



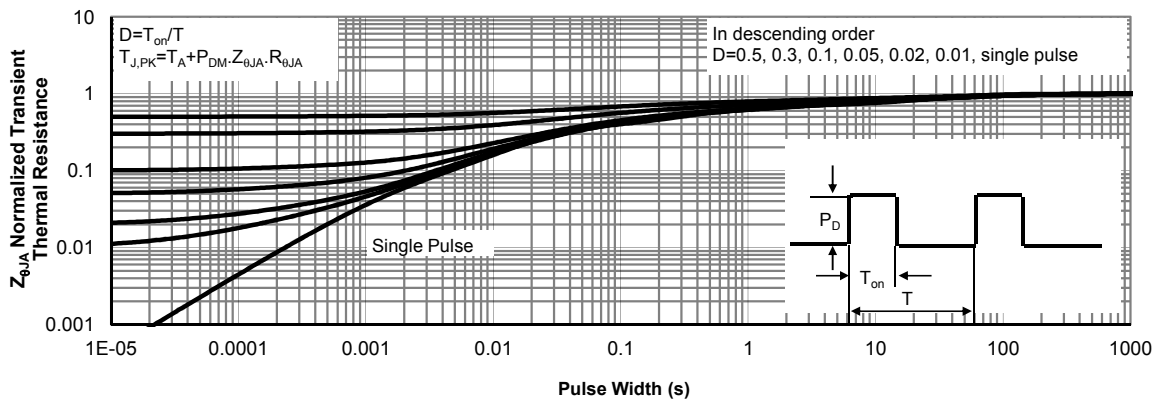
**Figure 7: Gate-Charge Characteristics**



**Figure 8: Maximum Forward Biased Safe Operating Area (Note1)**



**Figure 9: Single Pulse Power Rating Junction-to-Ambient (Note1)**



**Figure 10: Normalized Maximum Transient Thermal Impedance (Note1)**

